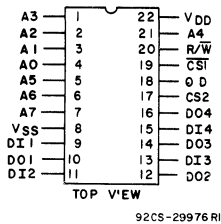


MWS5101



TERMINAL ASSIGNMENT

256-Word by 4-Bit LSI Static Random-Access Memory

Features:

- Industry standard pinout
- Very low operating current—8 mA at $V_{DD} = 5 V$ and cycle time = $1 \mu s$
- Two Chip-Select inputs—simple memory expansion
- Memory retention for standby battery voltage of 2 V min
- Output-Disable for common I/O systems
- 3-state data output for bus-oriented systems
- Separate data inputs and outputs

The RCA-MWS5101 is a 256-word by 4-bit static random-access memory designed for use in memory systems where high speed, very low operating current, and simplicity in use are desirable. It has separate data inputs and outputs and utilizes a single power supply of 4 to 6.5 volts.

Two Chip-Select inputs are provided to simplify system expansion. An Output Disable control provides Wire-OR capability and is also useful in common Input/Output systems by forcing the output into a high-impedance state during a write operation independent of the Chip-Select input condition. The output assumes a high-impedance state when the Output Disable is at high level or when the chip is deselected by $\overline{CS1}$ and/or CS2.

The high noise immunity of the CMOS technology is preserved in this design. For TTL interfacing at 5-V operation, excellent system noise margin is preserved by using an external pull-up resistor at each input.

For applications requiring wider temperature and operating voltage ranges, the mechanically and functionally equivalent static RAM, RCA-CDP1822, may be used

The MWS5101 types are supplied in 22-lead hermetic dual-in-line, side-brazed ceramic packages (D suffix), in 22-lead dual-in-line plastic packages (E suffix), and in chip form (H suffix).

OPERATIONAL MODES

| MODE | INPUTS | | | | OUTPUT |
|----------------|-----------------------------------|----------------------|----------------------|-------------------|----------------|
| | Chip Select 1 $\overline{CS1}$ | Chip Select 2 CS2 | Output Disable OD | Read/Write R/W | |
| READ | 0 | 1 | 0 | 1 | Read |
| WRITE | 0 | 1 | 0 | 0 | Data In |
| WRITE | 0 | 1 | 1 | 0 | High Impedance |
| STANDBY | 1 | X | X | X | High Impedance |
| STANDBY | X | 0 | X | X | High Impedance |
| OUTPUT DISABLE | X | X | 1 | X | High Impedance |

Logic 1 = High Logic 0 = Low X = Don't Care

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MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE (V_{DD})

(All voltage referenced to V_{SS} terminal) -0.5 to -7 V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5 to $V_{DD} + 0.5$ V

DC INPUT CURRENT, ANY ONE INPUT ± 10 mA

POWER DISSIPATION PER PACKAGE (P_D)

For $T_A = -40$ to $+60^\circ\text{C}$ (PACKAGE TYPE E) 500 mW

For $T_A = +60$ to $+85^\circ\text{C}$ (PACKAGE TYPE E) Derate Linearly at $12\text{ mW}/^\circ\text{C}$ to 200 mW

For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE D) 500 mW

For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE D) Derate Linearly at $12\text{ mW}/^\circ\text{C}$ to 200 mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR $T_A = \text{FULL PACKAGE-TEMPERATURE RANGE (All Package Types)}$ 100 mW

OPERATING-TEMPERATURE RANGE (T_A)

PACKAGE TYPE D -55 to $+125^\circ\text{C}$

PACKAGE TYPE E -40 to $+85^\circ\text{C}$

STORAGE TEMPERATURE RANGE (T_{stg}) -65 to $+150^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING)

At distance $1/16 \pm 1/32$ inch (1.59 ± 0.79 mm) from case for 10 s max $+265^\circ\text{C}$

OPERATING CONDITIONS at $T_A = \text{Full Package-Temperature Range}$

For maximum reliability, operating conditions should be selected so that operation is always within the following ranges:

| CHARACTERISTIC | LIMITS | | UNITS |
|----------------------------|-----------|----------|-------|
| | ALL TYPES | | |
| | Min. | Max. | |
| DC Operating-Voltage Range | 4 | 6.5 | V |
| Input Voltage Range | V_{SS} | V_{DD} | |

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STATIC ELECTRICAL CHARACTERISTICS at $T_A = 0$ to 70°C , $V_{DD} = 5\text{ V} \pm 5\%$.

| CHARACTERISTIC | TEST CONDITIONS | | LIMITS | | | UNITS | |
|---|--|-----------------|----------------------|-------|------|---------|---------------|
| | V_O (V) | V_{IN} (V) | MWS5101D MWS5101E | | | | |
| | | | Min. | Typ.* | Max. | | |
| Quiescent Device Current, I_{DD} | L2 Types | — | 0.5 | — | 25 | 50 | μA |
| | L3 Types | — | 0.5 | — | 100 | 200 | |
| Output Voltage: | Low-Level, V_{OL} | — | 0.5 | — | 0 | 0.1 | V |
| | High-Level, V_{OH} | — | 0.5 | 4.9 | 5 | — | |
| Input Low Voltage, V_{IL} | — | — | — | — | — | 1.5 | |
| Input High Voltage, V_{IH} | — | — | — | 3.5 | — | — | |
| Output Low (Sink) Current, I_{OL} | — | 0.4 | 0.5 | 2 | 4 | — | mA |
| | Output High (Source) Current, I_{OH} | 4.6 | 0.5 | -1 | -2 | — | |
| Input Current, I_{IN} | — | — | 0.5 | — | — | ± 5 | |
| 3-State Output Leakage Current, I_{OUT} | L2 Types | 0.5 | 0.5 | — | — | ± 5 | μA |
| | L3 Types | 0.5 | 0.5 | — | — | ± 5 | |
| Operating Current, $I_{DD1}^\#$ | — | — | 0.5 | — | 4 | 8 | mA |
| Input Capacitance, C_{IN} | — | — | — | — | 5 | 7.5 | pF |
| Output Capacitance, C_{OUT} | — | — | — | — | 10 | 15 | |

* Typical values are for $T_A = 25^\circ\text{C}$ and nominal V_{DD} .

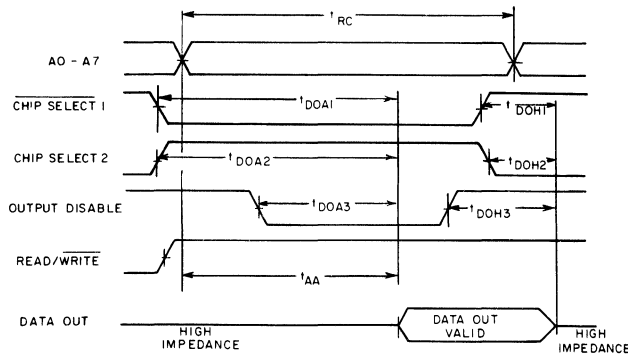
Outputs open-circuited, cycle time=1 μs .

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DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 0$ to 70°C , $V_{DD} = 5\text{ V} \pm 5\%$,
 $t_r, t_f = 20\text{ ns}$, $V_{IH} = 0.7 V_{DD}$, $V_{IL} = 0.3 V_{DD}$, $C_L = 100\text{ pF}$

| CHARACTERISTIC | LIMITS | | | | | | UNITS | |
|----------------------------------|--------------------|-------|------|----------|-------|------|-------|----|
| | MWS5101D, MWS5101E | | | | | | | |
| | L2 Types | | | L3 Types | | | | |
| | Min.† | Typ.● | Max. | Min.† | Typ.● | Max. | | |
| Read Cycle Times (Fig. 1) | | | | | | | | |
| Read Cycle | t_{RC} | 250 | – | – | 350 | – | – | ns |
| Access from Address | t_{AA} | – | 150 | 250 | – | 200 | 350 | |
| Output Valid from Chip-Select 1 | t_{DOA1} | – | 150 | 250 | – | 200 | 350 | |
| Output Valid from Chip-Select 2 | t_{DOA2} | – | 150 | 250 | – | 200 | 350 | |
| Output Valid from Output Disable | t_{DOA3} | – | – | 110 | – | – | 150 | |
| Output Hold from Chip-Select 1 | t_{DOH1} | 20 | – | – | 20 | – | – | |
| Output Hold from Chip-Select 2 | t_{DOH2} | 20 | – | – | 20 | – | – | |
| Output Hold from Output Disable | t_{DOH3} | 20 | – | – | 20 | – | – | |

- † Time required by a limit device to allow for the indicated function
- Typical values are for $T_A = 25^\circ\text{C}$ and nominal V_{DD}



92CM-30244R4

Fig. 1 - Read cycle timing waveforms

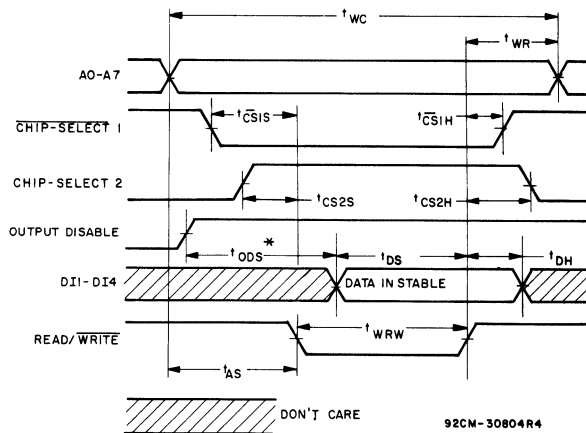
MWS5101

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 0$ to 70°C , $V_{DD} = 5\text{ V} \pm 5\%$,
 $t_r, t_f = 20\text{ ns}$, $V_{IH} = 0.7 V_{DD}$, $V_{IL} = 0.3 V_{DD}$, $C_L = 100\text{ pF}$

| CHARACTERISTIC | LIMITS | | | | | | UNITS | |
|----------------------------|--------------------|-------|------|----------|-------|------|-------|----|
| | MWS5101D, MWS5101E | | | | | | | |
| | L2 Types | | | L3 Types | | | | |
| | Min.† | Typ.● | Max. | Min.† | Typ.● | Max. | | |
| Write Cycle Times (Fig. 2) | | | | | | | | |
| Write Cycle | t_{WC} | 300 | — | — | 400 | — | — | ns |
| Address Setup | t_{AS} | 110 | — | — | 150 | — | — | |
| Write Recovery | t_{WR} | 40 | — | — | 50 | — | — | |
| Write Width | t_{WRW} | 150 | — | — | 200 | — | — | |
| Input Data Setup Time | t_{DS} | 150 | — | — | 200 | — | — | |
| Data In Hold | t_{DH} | 40 | — | — | 50 | — | — | |
| Chip-Select 1 Setup | t_{CS1S} | 110 | — | — | 150 | — | — | |
| Chip-Select 2 Setup | t_{CS2S} | 110 | — | — | 150 | — | — | |
| Chip-Select 1 Hold | t_{CS1H} | 0 | — | — | 0 | — | — | |
| Chip-Select 2 Hold | t_{CS2H} | 0 | — | — | 0 | — | — | |
| Output Disable Setup | t_{ODS} | 110 | — | — | 150 | — | — | |

- † Time required by a limit device to allow for the indicated function
- Typical values are for $T_A = 25^\circ\text{C}$ and nominal V_{DD}

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* t_{ODS} IS REQUIRED FOR COMMON I/O OPERATION ONLY. FOR SEPARATE I/O OPERATIONS, OUTPUT DISABLE IS DON'T CARE

Fig. 2 - Write cycle timing waveforms.

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DATA RETENTION CHARACTERISTICS at $T_A = 0$ to 70°C ; See Fig. 3

| CHARACTERISTIC | TEST CONDITIONS | | LIMITS | | | UNITS |
|---|-----------------|---------|-----------|-------|------|---------------|
| | VDR (V) | VDD (V) | All Types | | | |
| | | | Min. | Typ.* | Max. | |
| Minimum Data Retention Voltage, V_{DR} | — | — | — | 1.5 | 2 | V |
| Data Retention Quiescent Current, I_{DD} | L2 Types | — | — | 2 | 10 | μA |
| | L3 Types | | — | 5 | 50 | |
| Chip Deselect to Data Retention Time, t_{CDR} | — | 5 | 600 | — | — | ns |
| Recovery to Normal Operation Time, t_{RC} | — | 5 | 600 | — | — | |
| VDD to VDR Rise and Fall Time t_r, t_f | 2 | 5 | 1 | — | — | μs |

* Typical values are for $T_A = 25^\circ\text{C}$ and nominal V_{DD}

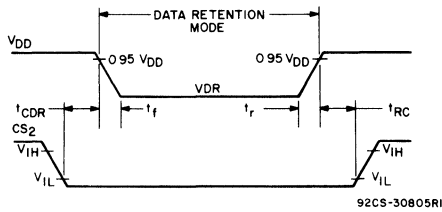


Fig. 3 - Low V_{DD} data retention timing waveforms.

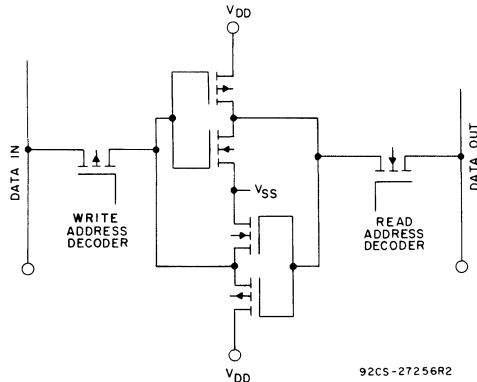
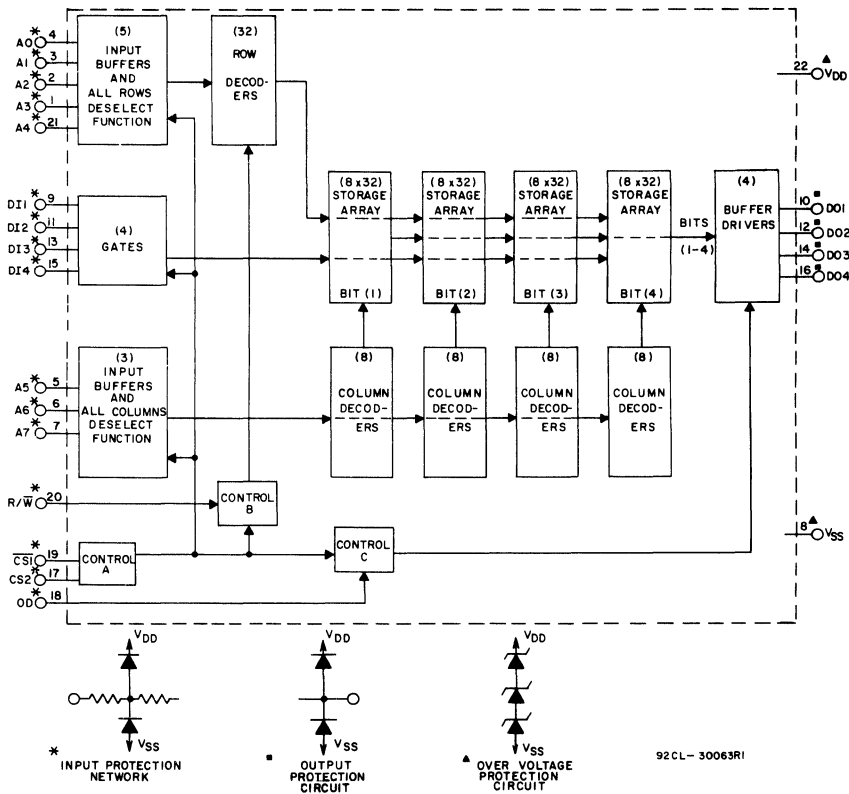


Fig. 4 - Memory cell configuration

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Fig 5 - Functional block diagram for MWS5101

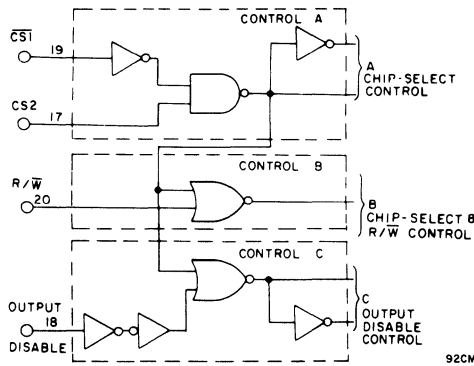


Fig 6 - Logic diagram of controls for MWS5101.